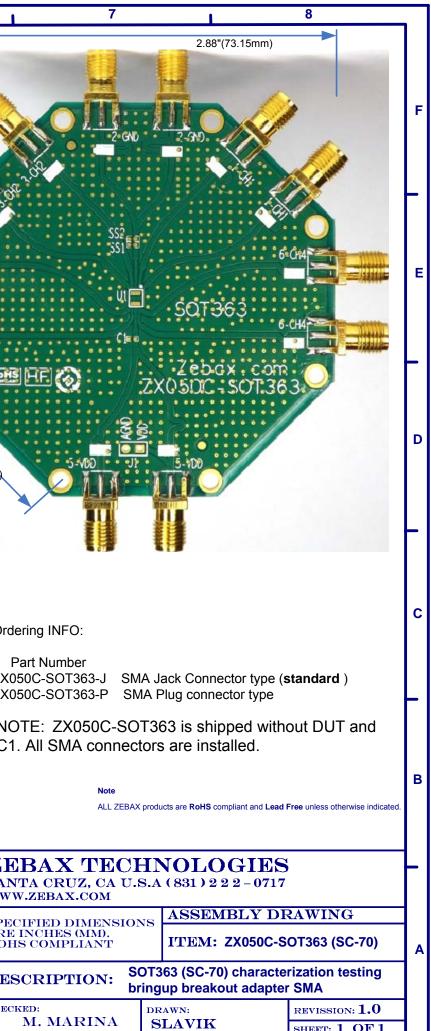
Γ.	1	1	2			3		1	4	1	5	1	6 1
	Product Name:	ZX050C-So	OT363 (S	C-70) S	ютз6з	(SC-70)	Character	ization testi	ng bringup	o breakou	t module		
F	Product Description:	High Speed of the devic as measure	ce under to	est- DUT,	nodule n U1, is a	neeting 10 accessible	)GHz sign via 2 ded	al bandwidth icated SMA o	with < 0.30 connectors	dB insertion for externa	n loss. Each pi al stimulus as w	n vell	
			50C-SOT	363 is des	igned w	ʻith 50 Ω (					T363 packaged . The module		2.88"(73.15mm)
		ldeal evalua package.	ation, brin	gup, and	testing o	of any dis	crete com	ponent such	as ESD dic	de using S	SOT363 footprir	nt	.4-CH3
E		is available μF or simila	for applic ar decoup	ations usi ling capac	ng pin 5 sitor.	of the D	UT as sup	ply rail to the	device. C1	can`be po	2 SMD package opulated with 0. AGND layers.	e) 1	1.09"(27.6mm)
								the module's removed, if r			ID, via onboard		
D	Application:	Bringup, Cl	haracteriz	ation, test	ing, dev	velopmen	t, modular	design evalu	ations	SIM <u>S</u>	blified Block Dia	igram:	SMA
	Target DUT :												1.09"(27.6mm)
	Pitch:	Standard SOT363 (SC-74R) SMD package or equivalent											
	Headers:	Ground acc	ound access test point (GND) - 0.025" SQ with 0.32" (5.6mm) post height										
	DUT landing pads:	ling pads: Surface Mount, 6 pin package – see table below											
С	DIMENTIONS (mm) UNIT Z	G	X	v	C1	C2						⊥ ⊥	SMA Orde
	mm Typical 2.50		0.42	0.600	1.90	0.65			:				P
	min					<b>←</b> C2 <b>→←</b> (	2 <b>2-&gt;</b>						ZX0
	OUTLINE Version		RENCES			+ +				NI : Not Installed SS5 and SS6 are 0402 SI each other via short trace	MD package footprint where the landing pads are connected . The trace can be cut if the GND connection is not required.	to	NO
	SOT323	C JEDEC	JEITA SC-70		↑ ┗			SMA:	. 500				C1
в					Z G			Impedanc Temp Rai		C +165°C			
						+ +	[+] ↓	Vibration:	MIL-	STD-202, I	Method 213	PLUG (	
						•ו	_	Frequenc Working \	-	DC – 1 335V m			1/436
$\left  - \right $								Withstand	Voltage:	1000V			↓ ZE
								Center Co Outer Cor		≤3mΩ ≤2mΩ		JACK (	J) SAN WWV
								Insulation	resistance	: ≥5000N		· · · ·	T. SPEC
Α	Notice							VSWR St	aight:	≤1.15 (	0.8-2.5G)		9.52mm(0.375")
		BAX TECHNOLOGIES DESIGN SPECIFICATIONS, DRAWINGS, PUBLICATIONS, AND OTHER DOCUMENTS (TOGETHER AND SEPARATELY, "MATERIALS") ARE BEING PROVIDED "AS IS." ZEBAX MAKES NO WARRANTIES, EXPRESSED, 0, STATUTORY, OR OTHERWISE WITH RESPECT TO THE MATERIALS, AND EXPRESSLY DISCLAIMS ALL IMPLIED WARRANTIES OF NO INFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE.									DES		
		mation furnished is believed to be accurate and reliable. However, Zebax Technologies assumes no responsibility for the consequences of use of such information or for any infringement of patents or other rights of third parties that may result from its use.											CHECH
Ľ	1	l	2	Í		3			4		5	Í	<u> </u>



SHEET: 1 OF 1